**Welcome to **

What is "**Embedded - Microcontrollers**"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "**Embedded - Microcontrollers**"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f256ht-i-mr

TABLE 4: PIN NAMES FOR 100-PIN DEVICES

100-PIN TQFP (TOP VIEW)[1,2,3]

PIC32MX330F064L
PIC32MX350F128L
PIC32MX350F256L
PIC32MX370F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RG15	36	V_{SS}
2	V_{DD}	37	V_{DD}
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	RPF13/RF13
5	AN27/PMD7/RE7	40	RPF12/RF12
6	RPC1/RC1	41	AN12/PMA11/RB12
7	RPC2/RC2	42	AN13/PMA10/RB13
8	RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	V_{SS}
11	AN17/C1INC/RPG7/PMA4/RG7	46	V_{DD}
12	AN18/C2IND/RPG8/PMA3/RG8	47	RPD14/RD14
13	$\overline{MCLR}$	48	RPD15/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	V_{SS}	50	RPF5/PMA8/RF5
16	V_{DD}	51	RPF3/RF3
17	TMS/CTED1/RA0	52	RPF2/RF2
18	RPE8/RE8	53	RPF8/RF8
19	RPE9/RE9	54	RPF7/RF7
20	AN5/C1INA/RPB5/RB5	55	RPF6/SCK1/INT0/RF6
21	AN4/C1INB/RB4	56	SDA1/RG3
22	PGED3/AN3/C2INA/RPB3/RB3	57	SCL1/RG2
23	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	V_{DD}
28	V_{REF}-/CV_{REF}-/PMA7/RA9	63	OSC1/CLKI/RC12
29	V_{REF}+/CV_{REF}+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AV_{DD}	65	V_{SS}
31	AV_{SS}	66	RPA14/RA14
32	AN8/RPB8/CTED10/RB8	67	RPA15/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CV_{REFOUT}/AN10/RPB10/CTED11PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/PMCS2/RD10

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: RPF6 (pin 55) and RPF7 (pin 54) are only remappable for input functions.

TABLE 5:   PIN NAMES FOR 100-PIN DEVICES

100-PIN TQFP (TOP VIEW)[1,2]

PIC32MX430F064L
PIC32MX450F128L
PIC32MX450F256L
PIC32MX470F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RG15	36	Vss
2	VDD	37	VDD
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	RPF13/RF13
5	AN27/PMD7/RE7	40	RPF12/RF12
6	RPC1/RC1	41	AN12/PMA11/RB12
7	RPC2/RC2	42	AN13/PMA10/RB13
8	RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	Vss
11	AN17/C1INC/RPG7/PMA4/RG7	46	VDD
12	AN18/C2IND/RPG8/PMA3/RG8	47	RPD14/RD14
13	$\overline{\text{MCLR}}$	48	RPD15/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	Vss	50	RPF5/PMA8/RF5
16	VDD	51	USBID/RF3
17	TMS/CTED1/RA0	52	RPF2/RF2
18	RPE8/RE8	53	RPF8/RF8
19	RPE9/RE9	54	VBUS
20	AN5/C1INA/RPB5/VBUSON/RB5	55	VUSB3V3
21	AN4/C1INB/RB4	56	D-
22	PGED3/AN3/C2INA/RPB3/RB3	57	D+
23	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	VDD
28	VREF-/CVREF-/PMA7/RA9	63	OSC1/CLKI/RC12
29	VREF+/CVREF+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AVDD	65	Vss
31	AVss	66	SCL1/RPA14/RA14
32	AN8/RPB8/CTED10/RB8	67	SDA1/RPA15/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/SCK1/PMCS2/RD10

Note   **1:**   The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

   2:   Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

PIC32MX330/350/370/430/450/470

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
RB0	16	25	B14	I/O	ST	
RB1	15	24	A15	I/O	ST	
RB2	14	23	B13	I/O	ST	
RB3	13	22	A13	I/O	ST	
RB4	12	21	B11	I/O	ST	
RB5	11	20	A12	I/O	ST	
RB6	17	26	A20	I/O	ST	
RB7	18	27	B16	I/O	ST	
RB8	21	32	A23	I/O	ST	PORTB is a bidirectional I/O port
RB9	22	33	B19	I/O	ST	
RB10	23	34	A24	I/O	ST	
RB11	24	35	B20	I/O	ST	
RB12	27	41	B23	I/O	ST	
RB13	28	42	A28	I/O	ST	
RB14	29	43	B24	I/O	ST	
RB15	30	44	A29	I/O	ST	
RC1	—	6	A5	I/O	ST	
RC2	—	7	B4	I/O	ST	
RC3	—	8	A6	I/O	ST	
RC4	—	9	B5	I/O	ST	PORTC is a bidirectional I/O port
RC12	39	63	B34	I/O	ST	
RC13	47	73	A47	I/O	ST	
RC14	48	74	B40	I/O	ST	
RC15	40	64	A42	I/O	ST	
RD0	46	72	B39	I/O	ST	
RD1	49	76	A52	I/O	ST	
RD2	50	77	B42	I/O	ST	
RD3	51	78	A53	I/O	ST	
RD4	52	81	B44	I/O	ST	
RD5	53	82	A55	I/O	ST	
RD6	54	83	B45	I/O	ST	
RD7	55	84	A56	I/O	ST	PORTD is a bidirectional I/O port
RD8	42	68	B37	I/O	ST	
RD9	43	69	A45	I/O	ST	
RD10	44	70	B38	I/O	ST	
RD11	45	71	A46	I/O	ST	
RD12	—	79	B43	I/O	ST	
RD13	—	80	A54	I/O	ST	
RD14	—	47	B26	I/O	ST	
RD15	—	48	A31	I/O	ST	

Legend: CMOS = CMOS compatible input or output   Analog = Analog input   P = Power
ST = Schmitt Trigger input with CMOS levels   O = Output   I = Input
TTL = TTL input buffer

Note 1: This pin is only available on devices without a USB module.
    2: This pin is only available on devices with a USB module.
    3: This pin is not available on 64-pin devices.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- C_{IN} = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- C_{OUT} = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \}$$
$$+\ estimated\ oscillator\ PCB\ stray\ capacitance$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$
$$= \{([20][20]) / [40] \} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~V_{DD}-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with $\leq$ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS
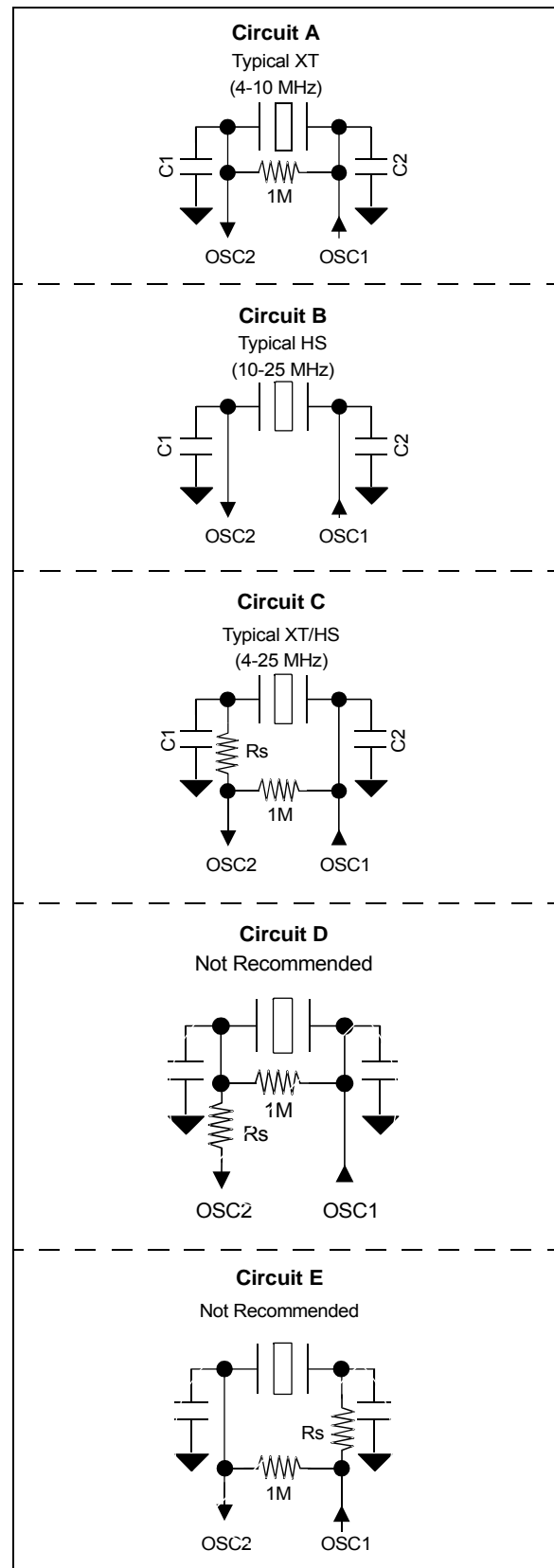
REGISTER 4-4: **BMXDUPBA: DATA RAM USER PROGRAM BASE ADDRESS REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUPBA<7:0>							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDUPBA<15:10>:** DRM User Program Base Address bits

When non-zero, the value selects the relative base address for User mode program space in RAM, BMXDUPBA must be greater than BMXDUDBA.

bit 9-0 **BMXDUPBA<9:0>:** Read-Only bits

Value is always '0', which forces 1 KB increments

Note 1:	At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernel mode data usage.
2:	The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 9-6: CHEW1: CACHE WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW1<31:24>							
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW1<23:16>							
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW1<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW1<7:0>							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-0 **CHEW1<31:0>:** Word 1 of the cache line selected by the CHEIDX<3:0> bits (CHEACC<3:0>)
Readable only if the device is not code-protected.

REGISTER 9-7: CHEW2: CACHE WORD 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW2<31:24>							
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW2<23:16>							
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW2<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW2<7:0>							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-0 **CHEW2<31:0>:** Word 2 of the cache line selected by the CHEIDX<3:0> bits (CHEACC<3:0>)
Readable only if the device is not code-protected.

REGISTER 10-7: DCHxCON: DMA CHANNEL 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	CHBUSY	—	—	—	—	—	—	CHCHNS[1]
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R/W-0	R/W-0
	CHEN[2]	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>	

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **CHBUSY:** Channel Busy bit
1 = Channel is active or has been enabled
0 = Channel is inactive or has been disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **CHCHNS:** Chain Channel Selection bit[1]
1 = Chain to channel lower in natural priority (CH1 will be enabled by CH2 transfer complete)
0 = Chain to channel higher in natural priority (CH1 will be enabled by CH0 transfer complete)

bit 7 **CHEN:** Channel Enable bit[2]
1 = Channel is enabled
0 = Channel is disabled

bit 6 **CHAED:** Channel Allow Events If Disabled bit
1 = Channel start/abort events will be registered, even if the channel is disabled
0 = Channel start/abort events will be ignored if the channel is disabled

bit **CHCHN:** Channel Chain Enable bit
1 = Allow channel to be chained
0 = Do not allow channel to be chained

bit 4 **CHAEN:** Channel Automatic Enable bit
1 = Channel is continuously enabled, and not automatically disabled after a block transfer is complete
0 = Channel is disabled on block transfer complete

bit 3 **Unimplemented:** Read as '0'

bit 2 **CHEDET:** Channel Event Detected bit
1 = An event has been detected
0 = No events have been detected

bit 1-0 **CHPRI<1:0>:** Channel Priority bits
11 = Channel has priority 3 (highest)
10 = Channel has priority 2
01 = Channel has priority 1
00 = Channel has priority 0

Note 1: The chain selection bit takes effect when chaining is enabled (i.e., CHCHN = 1).

2: When the channel is suspended by clearing this bit, the user application should poll the CHBUSY bit (if available on the device variant) to see when the channel is suspended, as it may take some clock cycles to complete a current transaction before the channel is suspended.

REGISTER 10-9: **DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER (CONTINUED)**

bit 4 **CHDHIF:** Channel Destination Half Full Interrupt Flag bit

1 = Channel Destination Pointer has reached midpoint of destination (CHDPTR = CHDSIZ/2)
0 = No interrupt is pending

bit 3 **CHBCIF:** Channel Block Transfer Complete Interrupt Flag bit

1 = A block transfer has been completed (the larger of CHSSIZ/CHDSIZ bytes has been transferred), or a pattern match event occurs
0 = No interrupt is pending

bit 2 **CHCCIF:** Channel Cell Transfer Complete Interrupt Flag bit

1 = A cell transfer has been completed (CHCSIZ bytes have been transferred)
0 = No interrupt is pending

bit 1 **CHTAIF:** Channel Transfer Abort Interrupt Flag bit

1 = An interrupt matching CHAIRQ has been detected and the DMA transfer has been aborted
0 = No interrupt is pending

bit 0 **CHERIF:** Channel Address Error Interrupt Flag bit

1 = A channel address error has been detected
Either the source or the destination address is invalid.
0 = No interrupt is pending

REGISTER 11-1: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	U-0	R/WC-0, HS
	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF

Legend:		
	WC = Write '1' to clear	HS = Hardware Settable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **IDIF:** ID State Change Indicator bit

1 = Change in ID state is detected
0 = No change in ID state is detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit

1 = 1 millisecond timer has expired
0 = 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit

1 = USB line state has been stable for 1millisecond, but different from last time
0 = USB line state has not been stable for 1 millisecond

bit 4 **ACTVIF:** Bus Activity Indicator bit

1 = Activity on the D+, D-, ID or VBUS pins has caused the device to wake-up
0 = Activity has not been detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit

1 = VBUS voltage has dropped below the session end level
0 = VBUS voltage has not dropped below the session end level

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit

1 = A change on the session end input was detected
0 = No change on the session end input was detected

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit

1 = Change on the session valid input is detected
0 = No change on the session valid input is detected

NOTES:

REGISTER 18-1:   SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 4   **DISSDI:** Disable SDI bit
1 = SDI pin is not used by the SPI module (pin is controlled by PORT function)
0 = SDI pin is controlled by the SPI module

bit 3-2   **STXISEL<1:0>:** SPI Transmit Buffer Empty Interrupt Mode bits
11 = Interrupt is generated when the buffer is not full (has one or more empty elements)
10 = Interrupt is generated when the buffer is empty by one-half or more
01 = Interrupt is generated when the buffer is completely empty
00 = Interrupt is generated when the last transfer is shifted out of SPISR and transmit operations are complete

bit 1-0   **SRXISEL<1:0>:** SPI Receive Buffer Full Interrupt Mode bits
11 = Interrupt is generated when the buffer is full
10 = Interrupt is generated when the buffer is full by one-half or more
01 = Interrupt is generated when the buffer is not empty
00 = Interrupt is generated when the last word in the receive buffer is read (i.e., buffer is empty)

Note 1:   When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2:   This bit can only be written when the ON bit = 0.

3:   This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4:   When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

19.0 INTER-INTEGRATED CIRCUIT (I^{2}C)

Note:	This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Inter-Integrated Circuit (I^{2}C)"** (DS60001116), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The I^{2}C module provides complete hardware support for both Slave and Multi-Master modes of the I^{2}C serial communication standard. Figure 19-1 illustrates the I^{2}C module block diagram.

Each I^{2}C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^{2}C module offers the following key features:

- I^{2}C interface supporting both master and slave operation
- I^{2}C Slave mode supports 7-bit and 10-bit addressing
- I^{2}C Master mode supports 7-bit and 10-bit addressing
- I^{2}C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for the I^{2}C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^{2}C supports multi-master operation; detects bus collision and arbitrates accordingly
- Provides support for address bit masking

REGISTER 28-6: **DEVID: DEVICE AND REVISION ID REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0>[1]				DEVID<27:24>[1]			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16>[1]							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8>[1]							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0>[1]							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 31-28   **VER<3:0>:** Revision Identifier bits[1]

bit 27-0   **DEVID<27:0>:** Device ID[1]

Note 1: See the *"PIC32 Flash Programming Specification"* (DS60001145) for a list of Revision and Device ID values.

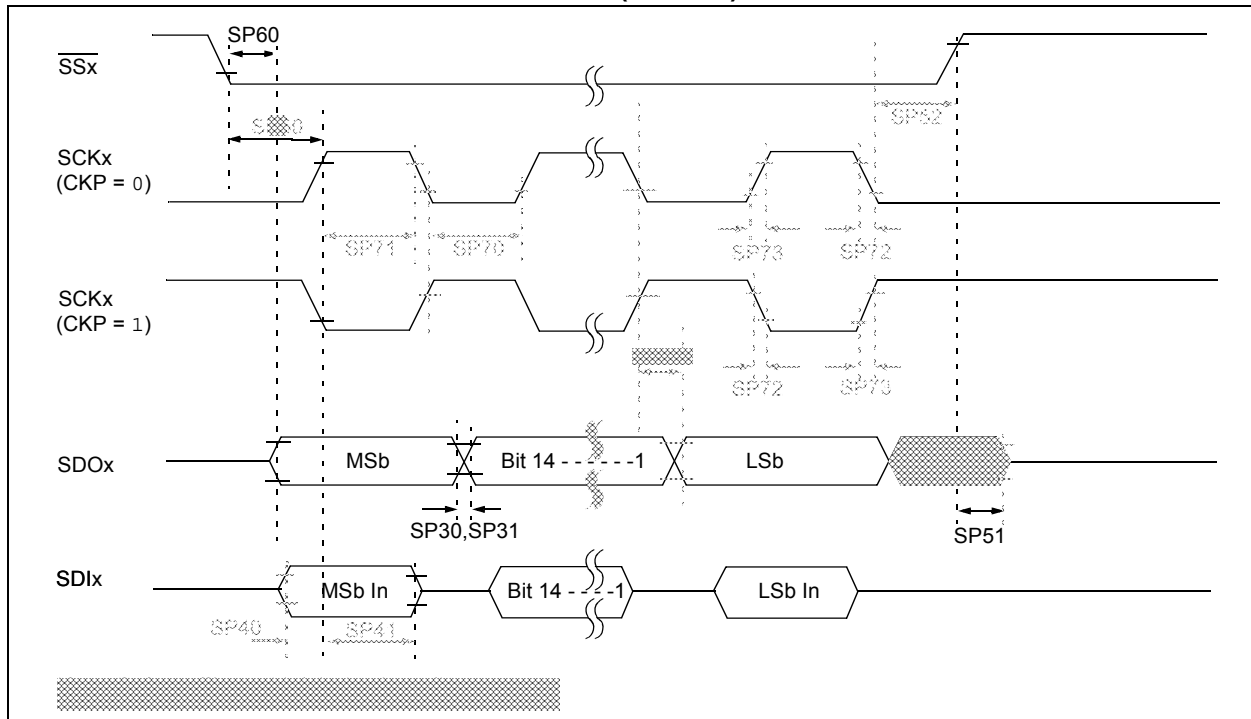**FIGURE 31-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS**

TABLE 31-32: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics[1]	Min.	Typical[2]	Max.	Units	Conditions
SP70	T_{ScL}	SCKx Input Low Time **(Note 3)**	$T_{SCK}/2$	—	—	ns	—
SP71	T_{ScH}	SCKx Input High Time **(Note 3)**	$T_{SCK}/2$	—	—	ns	—
SP72	T_{ScF}	SCKx Input Fall Time	—	5	10	ns	—
SP73	T_{ScR}	SCKx Input Rise Time	—	5	10	ns	—
SP30	T_{DOF}	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	T_{DOR}	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	$T_{ScH2DOV}$, $T_{ScL2DOV}$	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	$V_{DD} > 2.7V$
			—	—	30	ns	$V_{DD} < 2.7V$
SP40	$T_{DIV2ScH}$, $T_{DIV2ScL}$	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	$T_{ScH2DIL}$, $T_{ScL2DIL}$	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-32: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics[1]	Min.	Typical[2]	Max.	Units	Conditions
SP50	$T_{SSL2SCH}$, $T_{SSL2SCL}$	$\overline{SSx} \downarrow$ to SCKx $\downarrow$ or SCKx $\uparrow$ Input	175	—	—	ns	—
SP51	$T_{SSH2DOZ}$	$\overline{SSx} \uparrow$ to SDOx Output High-Impedance (Note 4)	5	—	25	ns	—
SP52	$T_{SCH2SSH}$ $T_{SCL2SSH}$	$\overline{SSx} \uparrow$ after SCKx Edge	T_{SCK} + 20	—	—	ns	—
SP60	$T_{SSL2DOV}$	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

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TABLE 31-34: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	Symbol	Characteristics		Min.	Max.	Units	Conditions
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode (Note 1)	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode (Note 1)	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode (Note 1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode (Note 1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode (Note 1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode (Note 1)	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode (Note 1)	250	—	ns	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode (Note 1)	250	—	ns	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode (Note 1)	600	—	ns	

Note 1:   Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

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TABLE 31-35: ADC MODULE SPECIFICATIONS (CONTINUED)

AC CHARACTERISTICS[5]			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $0°C \leq T_A \leq +70°C$ for Commercial $-40°C \leq T_A \leq +85°C$ for Industrial $-40°C \leq T_A \leq +105°C$ for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical	Max.	Units	Conditions
ADC Accuracy – Measurements with Internal V_{REF+}/V_{REF-}							
AD20d	Nr	Resolution		10 data bits		bits	(Note 3)
AD21d	INL	Integral Nonlinearity	> -1	—	< 1	LSb	$V_{INL} = AV_{SS} = 0V$, $AV_{DD} = 2.5V$ to 3.6V (Note 3)
AD22d	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	$V_{INL} = AV_{SS} = 0V$, $AV_{DD} = 2.5V$ to 3.6V (Notes 2,3)
AD23d	G_{ERR}	Gain Error	> -4	—	< 4	LSb	$V_{INL} = AV_{SS} = 0V$, $AV_{DD} = 2.5V$ to 3.6V (Note 3)
AD24d	E_{OFF}	Offset Error	> -2	—	< 2	LSb	$V_{INL} = AV_{SS} = 0V$, $AV_{DD} = 2.5V$ to 3.6V (Note 3)
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD31b	SINAD	Signal to Noise and Distortion	55	58	—	dB	(Notes 3,4)
AD34b	ENOB	Effective Number of Bits	9	9.5	—	bits	(Notes 3,4)

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN}. Refer to parameter BO10 in Table 31-10 for V_{BORMIN} values.

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FIGURE 31-22:   PARALLEL MASTER PORT WRITE TIMING DIAGRAM
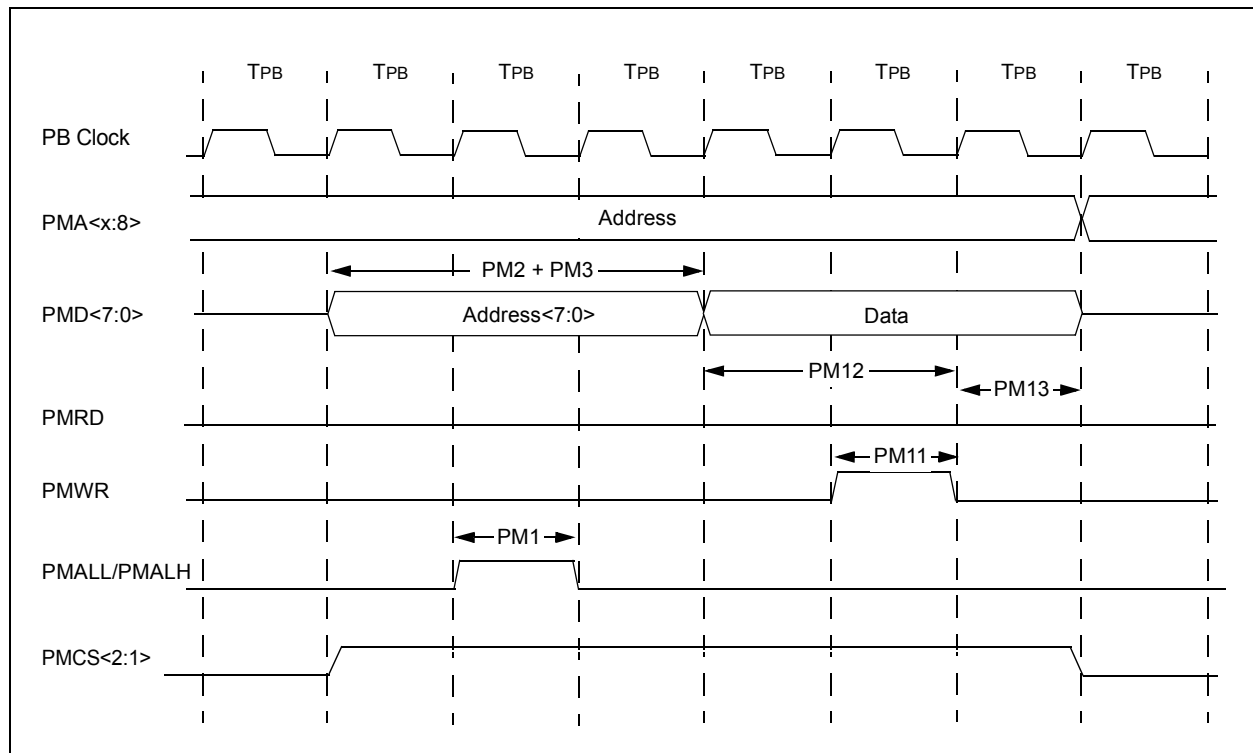

TABLE 31-40:   PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics[1]	Min.	Typ.	Max.	Units	Conditions
PM11	T_{WR}	PMWR Pulse Width	—	1 T_{PB}	—	—	—
PM12	T_{DVSU}	Data Out Valid before PMWR or PMENB goes Inactive (data setup time)	—	2 T_{PB}	—	—	—
PM13	T_{DVHOLD}	PMWR or PMEMB Invalid to Data Out Invalid (data hold time)	—	1 T_{PB}	—	—	—

**Note 1:**   These parameters are characterized, but not tested in manufacturing.

33.2   Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging
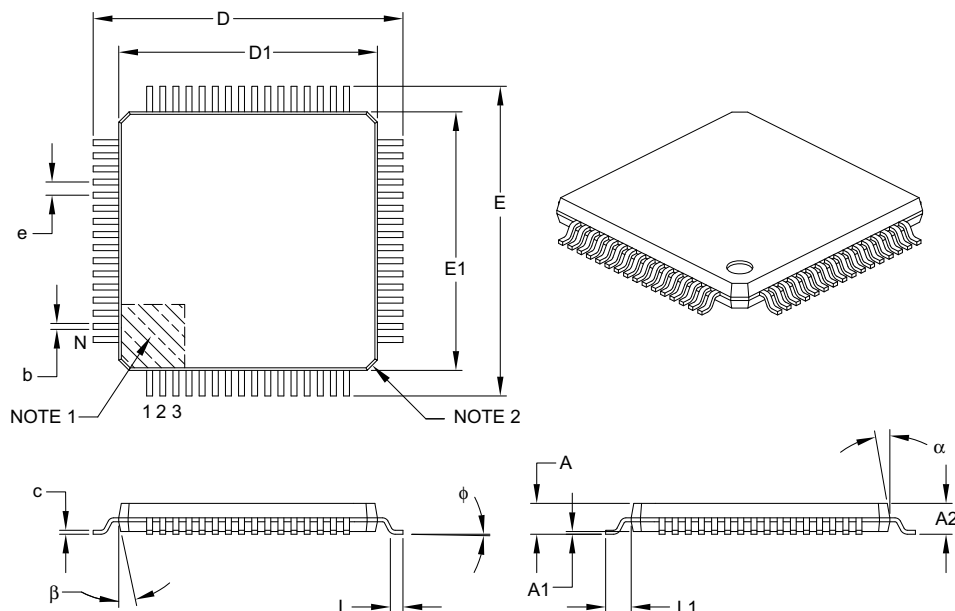
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

100-Lead Plastic Thin Quad Flatpack (PT)‑12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

RECOMMENDED LAND PATTERN
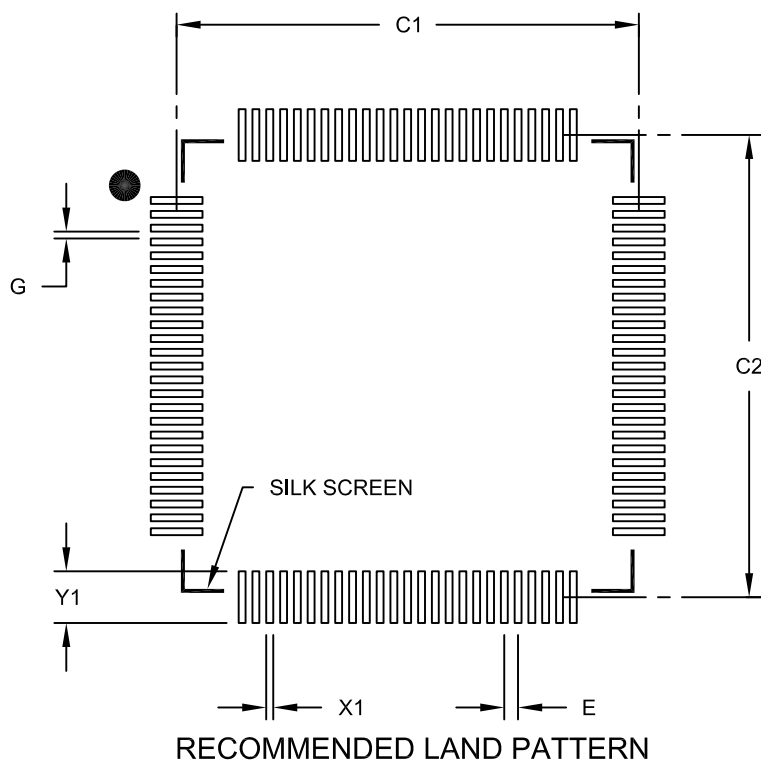
	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B